

XP-002183612

- AN - 1995-072189 [10]
AP - JP19930163258 19930608
CPY - HITB
DC - A21 A85 L03 P75 P84 V04 X12
FS - CPI;GMPI;EPI
IC - B41N1/22 ; C08G59/62 ; C08K5/13 ; C08L63/00 ; G03F7/004 ; G03F7/038 ; H05K1/03
MC - A05-A01E2 A05-C01A A08-D A08-R01 A12-E07A L03-H04E1
- V04-R07L X12-E02B
PA - (HITB) HITACHI CHEM CO LTD
PN - JP6350211 A 19941222 DW199510 H05K1/03 005pp
PR - JP19930163258 19930608
XA - C1995-032620
XIC - B41N-001/22 ; C08G-059/62 ; C08K-005/13 ; C08L-063/00 ; G03F-007/004 ; G03F-007/038 ; H05K-001/03
XP - N1995-056985
AB - J06350211 The epoxy resin compsn. for printed wiring board is formed by blending: (a) an epoxy resin; (b) a multifunctional phenolic resin; (c) an inorganic filler; and (d) a reducing agent as essential components. The reducing agent comprises a phenol-based reducing agent, or a bisphenol-based reducing agent.
- Pref. the epoxy resin comprises a cpd. having at least two epoxy gps. in a molecule, e.g. a bisphenol A type epoxy resin, bisphenol F type epoxy resin, bisphenol S type epoxy resin, bisphenol type epoxy resin, phenol novolak type epoxy resin, etc.. The multifunctional phenolic resin comprises a multifunctional phenolic resin having at least two hydroxyl gps. in one molecule, e.g. bisphenol A, bisphenol F, polyvinyl phenol, bisphenol or phenol, cresol, alkyl phenol, catechol, bisphenol A, bisphenol F, or their halide. The inorganic filler comprises aluminium hydroxide, calcium carbonate, alumina, titanium oxide, mica, clay, aluminium carbonate, magnesium silicate, aluminium silicate, antimony trioxide, silica, or glass short fibre.
- USE/ADVANTAGE - The epoxy resin compsn. is used for a printed wiring board. The resulting printed wiring board has low dimension change and enhanced metal migration resistance without decreasing the other properties.(Dwg.0/0)
IW - POLYEPOXIDE RESIN COMPOSITION PRINT WIRE BOARD COMPRISE MIXTURE
POLYEPOXIDE RESIN MULTIFUNCTION PHENOLIC RESIN INORGANIC FILL REDUCE AGENT COMPRISE DI PHENOL BASED REDUCE AGENT
IKW - POLYEPOXIDE RESIN COMPOSITION PRINT WIRE BOARD COMPRISE MIXTURE
POLYEPOXIDE RESIN MULTIFUNCTION PHENOLIC RESIN INORGANIC FILL REDUCE AGENT COMPRISE DI PHENOL BASED REDUCE AGENT
NC - 001
OPD - 1993-06-08
ORD - 1994-12-22
PAW - (HITB) HITACHI CHEM CO LTD
TI - Epoxy] resin compsn. for printed wiring board - comprises mixt. of epoxy] resin, multifunctional phenolic resin, inorganic filler and reducing agent comprising (bis)phenol-based reducing agent
A01 - [001] 017 ; H0022 H0011 ; G1570-R G1558 D01 D11 D10 D23 D22 D31 D42 D50 D69 D83 F47 7A ; G1150-R G1149 G1092 D01 D18 F32 F30 ; P0464-R

D01 D22 D42 F47 ; M9999 M2073 ;
 - [002] 017 ; H0022 H0011 ; G1570-R G1558 D01 D11 D10 D23 D22 D31 D42
 D50 D69 D83 F47 7A ; R00470 G1161 G1150 G1149 G1092 D01 D11 D10 D19
 D18 D32 D50 D93 F32 F30 ; P0464-R D01 D22 D42 F47 ; M9999 M2073 ;
 P0475 ;
 - [003] 017 ; H0022 H0011 ; G1570-R G1558 D01 D11 D10 D23 D22 D31 D42
 D50 D69 D83 F47 7A ; R12487 G1207 G1150 G1149 G1092 D01 D11 D10 D19
 D18 D32 D50 D93 F32 F30 ; P0464-R D01 D22 D42 F47 ; M9999 M2073 ;
 - [004] 017 ; H0022 H0011 ; G1570-R G1558 D01 D11 D10 D23 D22 D31 D42
 D50 D69 D83 F47 7A ; R00473 G1230 G1150 G1149 G1092 D01 D19 D18 D32
 D50 D92 F32 F30 F61 ; P0464-R D01 D22 D42 F47 ; M9999 M2073 ;
 - [005] 017 ; G1092-R D01 D18 F30 ; P0497 P0464 P0226 P0282 M2175 D01
 D18 ; H0011-R ; M9999 M2073 ;
 - [006] 017 ; ND04 ; ND01 ; Q9999 Q7454 Q7330 ; B9999 B3758-R B3747 ;
 B9999 B3418-R B3372 ; N9999 N6439 ; K9449 ;
 - [007] 017 ; A999 A157-R ;
 - [008] 017 ; D00 G3010 F80 Al 3A Si 4A O- 6A F44 C- ; R02020 D00 D67
 F21 H- Al 3A O- 6A ; R01278 D00 F44 C- 4A O- 6A Ca 2A ; R01544 D00
 F20 Al 3A O- 6A ; R01966 D00 F20 Ti 4B Tr O- 6A ; R01949 D00 F80 O-
 6A Al 3A Si 4A ; R01541 D00 F80 Mg 2A O- 6A Si 4A ; R01527 G2482 D00
 F20 O- 6A Sb 5A ; R01694 D00 F20 O- 6A Si 4A ; G2891 D00 Si 4A ;
 A999 A237 ; S9999 S1092 S1070 ;
 - [009] 017 ; D01 D19 D18 D32 F32 F30 F31 D31 ; A999 A748 ;
 A02 - [001] 017 ; G1161-R G1150 G1149 G1092 D01 D11 D10 D19 D18 D32 F32 F30
 D69 7A-R D93 ; R00470 G1161 G1150 G1149 G1092 D01 D11 D10 D19 D18 D32
 D50 D93 F32 F30 ; P0226 P0282-R D01 D18 F30 ; A999 A157-R ; A999
 A782 ; H0011-R ;
 - [002] 017 ; G1207-R G1150 G1149 G1092 D01 D11 D10 D19 D18 D32 F32 F30
 D69 D93 7A-R ; R12487 G1207 G1150 G1149 G1092 D01 D11 D10 D19 D18 D32
 D50 D93 F32 F30 ; P0226 P0282-R D01 D18 F30 ; A999 A157-R ; A999
 A782 ; H0011-R ;
 - [003] 017 ; G1105-R G1092 D01 D18 F31 F30 D31 D69 D86 7A-R ; R00868
 G1105 G1092 D01 D19 D18 D31 D50 D86 F31 F30 ; P0226 P0282-R D01 D18
 F30 ; A999 A157-R ; A999 A782 ; H0011-R ;
 - [004] 017 ; G1116-R G1105 G1092 D01 D11 D10 D19 D18 D31 D50 D87 F31
 F30 D69 7A-R ; P0226 P0282-R D01 D18 F30 ; A999 A157-R ; A999 A782 ;
 H0011-R ;
 - [005] 017 ; G0179 G0102 G0022 D01 D12 D10 D19 D18 D31 D51 D53 D58 D88
 F31 F30 D69 7A-R ; H0000 ; A999 A157-R ; A999 A782 ; P1741 ;
 - [006] 017 ; G1105-R G1092 D01 D18 F31 F30 D11 D10 ; P0226 P0282-R
 D01 D18 F30 ; A999 A157-R ; A999 A782 ; H0011-R ;